Claims

1	1. A device, comprising:
2	a means for performing metal organic vapor phase epitaxy (MOVPE) on a surface
3	of a substrate; and
4	a means for performing hydride vapor phase epitaxy (HVPE) on the surface of the
5	substrate.
1	2. The device according to claim 40, wherein said device can transition from
2	MOVPE to HVPE in situ.
1	3. The device according to claim 41, wherein the substrate does not have to be
2	removed from the device between MOVPE and HVPE.
1	4. The device according to claim 42, wherein the substrate can be maintained at
2	elevated temperatures during transition from MOVPE to HVPE.
1	5. The device according to claim 41, wherein said device can also transition from
2	HVPE to MOVPE in situ.
1	6. The device according to claim 44, wherein said device can also transition from
2	HVPE to MOVPE in situ.
1	7. The device according to claim 45, wherein the substrate can be maintained at
2	elevated temperatures during transition from HVPE to MOVPE.
1	8. The device according to claim 40, wherein said device can be used to grow a
2	III-V nitride compound semiconductor onto the surface of the substrate.

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1	9. The device according to claim 47, wherein said device can be used to grow GaN
2	onto the surface of the substrate.

- 10. The device according to claim 48, wherein said means for performing HVPE comprises a hot wall reactor having a source zone, and
 - a downstream mixing zone,

wherein TMG can be reached with Hcl in the source zone to form a chlorinated gallium species, and wherein the chlorinated gallium species can combine with NH₃ in the downstream mixing zone and directed toward the substrate for deposition of GaN onto the substrate.

11. The device according to claim 48, wherein said means for performing MOVPE comprises a low pressure horizonal cold-wall MOCVD reactor.